



**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**
Form PTO-1449 (Modified)
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COMPLETE IF KNOWN

Sheet	1	of	4	Application Number	09/651,779
				Confirmation Number	2448
				Filing Date	August 30, 2000
				First Named Inventor	Scott E. Moore
				Group Art Unit	3723
				Examiner Name	Dung V. Nguyen
				Attorney Docket No.	108298515US

U.S. PATENT DOCUMENTS					
Examiner Initials*	Cite No.	U.S. Patent or Application		Name of Patentee or Inventor of Cited Document	Date of Publication or Filing Date of Cited Document
		NUMBER	Kind Code (if known)		
AA		U.S. Application No. <u>09/651,808</u> (Atty. Docket No. 4373US)		Chopra et al.	Filed <u>08/30/2000</u>
AB		U.S. Application No. <u>09/653,392</u> (Atty. Docket No. MTI-31044)		Chopra et al.	Filed <u>08/31/2000</u>
AC		U.S. Application No. <u>09/887,767</u> (Atty. Docket No. 10829.8515US2)		Lee et al.	Filed <u>06/21/2001</u>
AD		U.S. Application No. <u>09/888,002</u> (Atty. Docket No. 10829.8515US3)		Lee et al.	Filed <u>06/21/2001</u>
AE		U.S. Application No. <u>09/888,084</u> (Atty. Docket No. 10829.8515US1)		Lee et al.	Filed <u>06/21/2001</u>
AF		U.S. Application No. <u>10/230,463</u> (Atty. Docket No. 10829.8672US)		Lee et al.	Filed <u>08/29/2002</u>
AG		U.S. Application No. <u>10/230,602</u> (Atty. Docket No. 10829.8674US)		Chopra	Filed <u>08/29/2002</u>
AH		U.S. Application No. <u>10/230,628</u> (Atty. Docket No. 10829.8673US)		Lee et al.	Filed <u>08/29/2002</u>
AI		U.S. Application No. <u>10/230,970</u> (Atty. Docket No. 10829.8515US6)		Lee et al.	Filed <u>08/29/2002</u>
AJ		U.S. Application No. <u>10/230,972</u> (Atty. Docket No. 10829.8515US7)		Lee et al.	Filed <u>08/29/2002</u>
AK		U.S. Application No. <u>10/230,973</u> (Atty. Docket No. 10829.8515US8)		Lee et al.	Filed <u>08/29/2002</u>
AL		<u>5,244,534</u>		Yu et al.	<u>09/14/1993</u>
AM		<u>5,300,155</u>		Sandhu et al.	<u>04/05/1994</u>
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<i>Dung V. Nguyen</i>	<i>1-29-2003</i>

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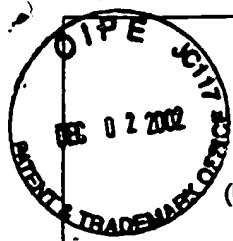
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Sheet 2 of 4 Attorney Docket No. 108298515US

U.S. PATENT DOCUMENTS						
Examiner Initials*	Cite No.	U.S. Patent or Application		Name of Patentee or Inventor of Cited Document	Date of Publication or Filing Date of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		NUMBER	Kind Code (if known)			
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BB		5,954,997		Kaufman et al.	09/21/1999	
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BG		6,051,496		Jang	04/18/2000	
BH		6,060,386		Givens	05/09/2000	
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BM		6,083,840		Mrvic et al.	07/04/2000	

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Sheet	3	of	4	Attorney Docket No.	108298515US
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BO		6,103,628		Talieh	08/15/2000	
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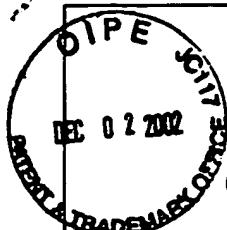
Examiner Initials*	Cite No.	Foreign Patent or Application		Name of Patentee or Applicant of Cited Document	Date of Publication or Filing Date of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	T
		Office	NUMBER				
CB	WO	00/26443		Talieh	05/11/2000		
CC	WO	00/28586		Chopra	05/18/2000		
CD	WO	00/32350		Talieh	06/08/2000		
CE	WO	00/59008		Talieh	10/05/2000		
CF	WO	00/59682		Talieh	10/12/2000		

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Examiner Initials*	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume/issue number(s), publisher, city and/or country where published.	T
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	CG	FRANKENTHAL, R.P. and EATON, D.H., "Electroetching of Platinum in the Titanium-Platinum-Gold Metallization on Silicon Integrated Circuits", <i>Journal of The Electrochemical Society</i> , Vol. 123, No. 5, pp. 703-706, May 1976.	
	CH	BERNHARDT, A.F., CONTOLINI, R.J., MAYER, S.T., "Electrochemical Planarization for Multi-Level Metallization of Microcircuitry", <i>Circuitree Journal</i> , Vol. 8, No. 10, pp. 38, 40, 42, 44, 46, and 48, Oct. 1995.	
	CI	HUANG, C.S. et al., "A Novel UV-Baking Process to Improve DUV-Photoresist Hardness", pp. 135-138.	
	CJ	McGraw-Hill, <i>Concise Encyclopedia of Science & Technology</i> , Sybil P. Parker, Editor-in-Chief, Fourth Edition, p. 367, McGraw-Hill, New York, New York, 1998.	
	CK	ATMI-Table-of-Contents, presented at the Semicon-West '99 Low-Dielectric-Materials Technology Conference, July 12, 1999, pp. 13-25.	
	CL	KONDŌ, S. et al., "Abrasive-Free-Polishing for Copper-Damascene-Interconnection", <i>Journal of the Electrochemical Society</i> , 147 (10) 3907-3913 (2000)	
	CM	Micro-Photonics, Inc., CSM-Application-Bulletin, "Low-load-Micro-Scratch-Tester (MST) for characterisation of thin polymer films", http://www.microphotonics.com/mstABpoly.html , 7/25/2002, 3 pages.	
	CN	Micro-Photonics, Inc., "GSM-Nano-Hardness-Tester", http://www.microphotonics.com/nht.html , 7/29/2002, 6 pages.	
	CO	PhysicsWorld—Table-of-Contents, PhysicsWeb, "Hard Materials", http://physicsweb.org/box/world/11/1/11/world-11-1-11-1 , 7/29/2002, 1 page.	

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